BAT54 Series

Small signal Schottky diodes

Main product characteristics

I_F	300 mA
V_{RRM}	40 V
C (typ)	7 pF
T_j (max)	150° C

Features and benefits

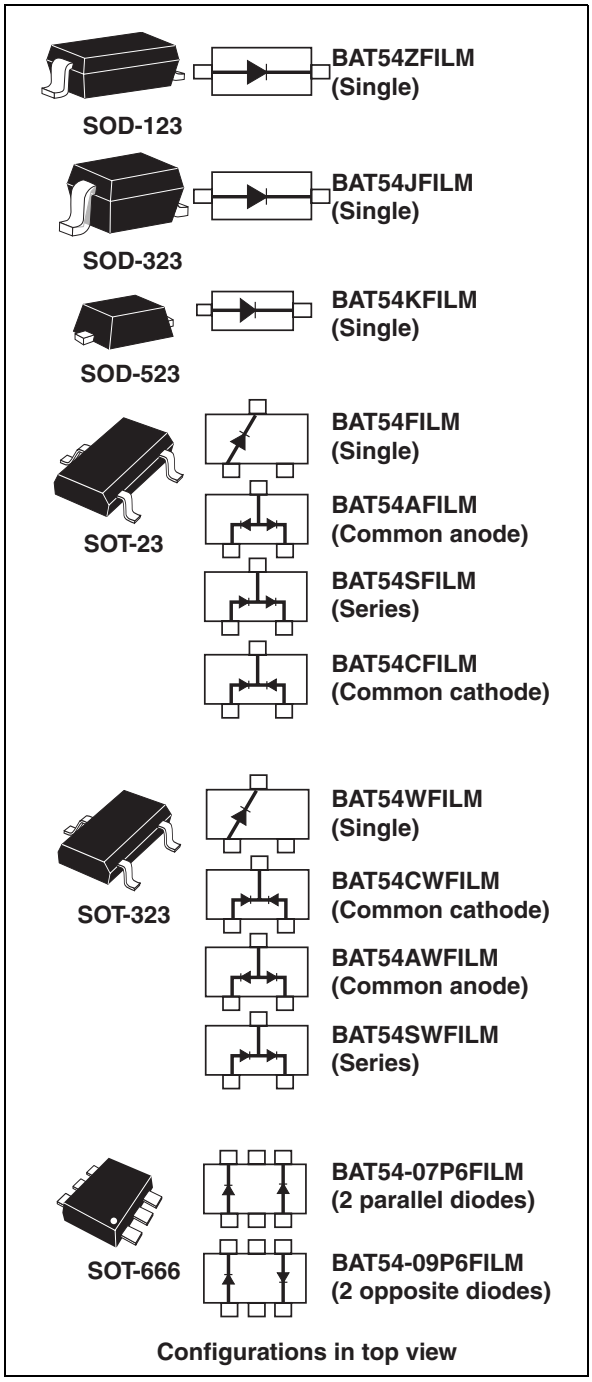
- Low conduction and reverse losses
- Negligible switching losses
- Low forward and reverse recovery times
- Extremely fast switching
- Surface mount device
- Low capacitance diode

Description

The BAT54 series uses 40 V Schottky barrier diodes packaged in SOD- 23, SOD-323, SOD-523, SOT-23, SOT-323, or SOT-666.

Order codes

Part Number	Marking
BAT54FILM	D86
BAT54SFILM	D88
BAT54CFILM	D87
BAT54AFILM	D84
BAT54WFILM	D73
BAT54SWFILM	D78
BAT54CWFILM	D77
BAT54AWFILM	D74
BAT54JFILM	86
BAT54KFILM	86
BAT54-07P6FILM	P4
BAT54-09P6FILM	Q4
BAT54ZFILM	D72



Configurations in top view

1 Characteristics

Table 1. Absolute ratings (limiting values at T_j = 25° C, unless otherwise specified)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		40	V
I_F	Continuous forward current		300	mA
I_{FSM}	Surge non repetitive forward current	t_p = 10 ms Sinusoidal	1	A
T_{stg}	Storage temperature range		-65 to +150	° C
T_j	Operating junction temperature range		-40 to +150	° C
T_L	Maximum soldering temperature		260	° C

Table 2. Thermal parameters

Symbol	Parameter		Value	Unit
$R_{th(j-a)}$	Junction to ambient(1)	SOT-23, SOD-123	500	°C/W
		SOT-323, SOD-323,	550	
		SOD-523, SOT-666	600	

1. Epoxy printed circuit board with recommended pad layout

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ	Max.	Unit
I_R(1)	Reverse leakage current	T_j = 25° C	V_R = 30 V			1	µA
		T_j = 100° C				100	
V_F(2)	Forward voltage drop	T_j = 25° C	I_F = 0.1 mA			240	mV
			I_F = 1 mA			320	
			I_F = 10 mA			400	
			I_F = 30 mA			500	
			I_F = 100 mA			900	

1. Pulse test: t_p = 5 ms, δ < 2 %
2. Pulse test: t_p = 380 µs, δ < 2 %

Table 4. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ	Max.	Unit
C	Diode capacitance	V_R = 1 V, F = 1 MHz		7	10	pF
t_{rr}	Reverse recovery time	I_F = 10 mA, I_R = 10 mA, T_j = 25° C I_{rr} = 1 mA, R_L = 100 Ω			5	ns

Figure 1. Average forward power dissipation versus average forward current

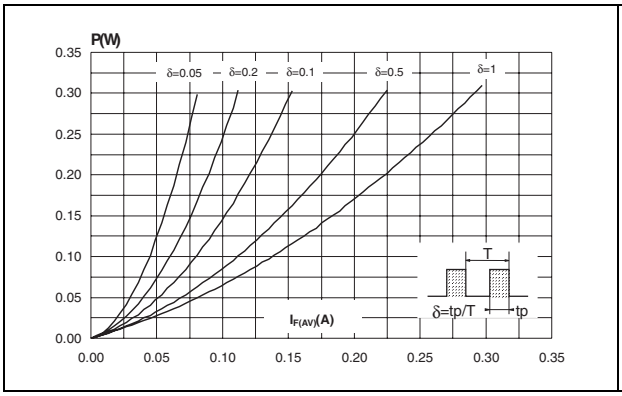


Figure 2. Average forward current versus ambient temperature (δ = 1)

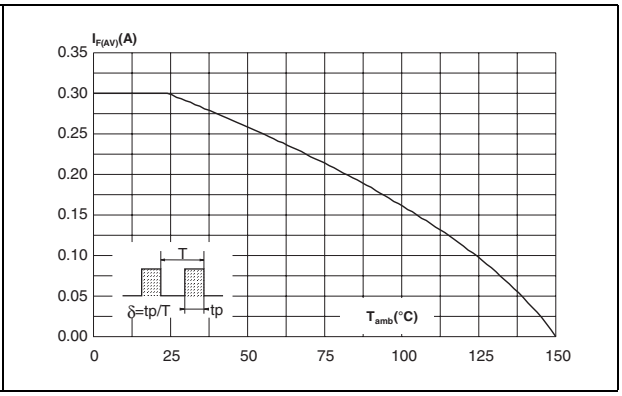


Figure 3. Reverse leakage current versus reverse applied voltage (typical values)

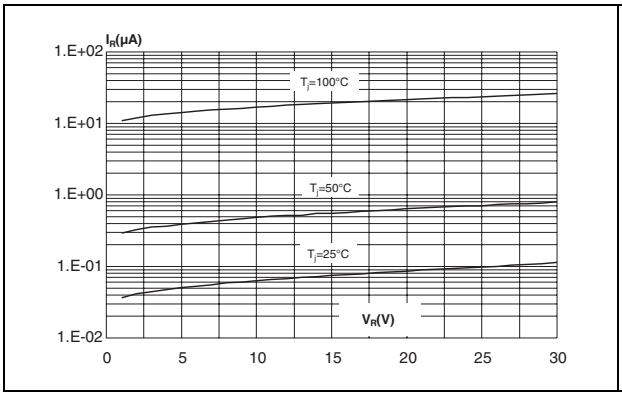


Figure 4. Reverse leakage current versus junction temperature

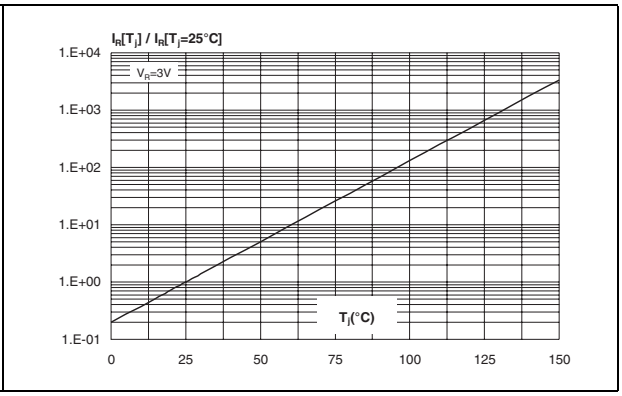


Figure 5. Junction capacitance versus reverse applied voltage (typical values)

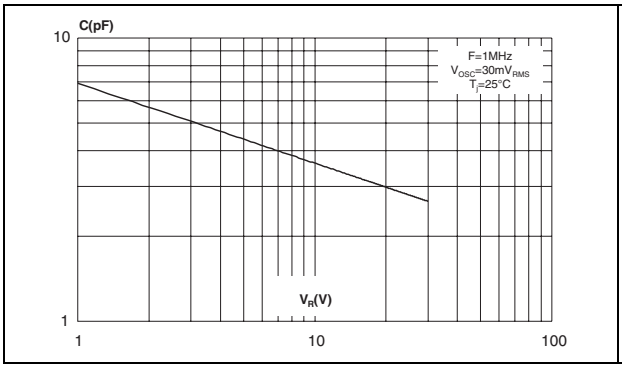


Figure 6. Forward voltage drop versus forward current (typical values)

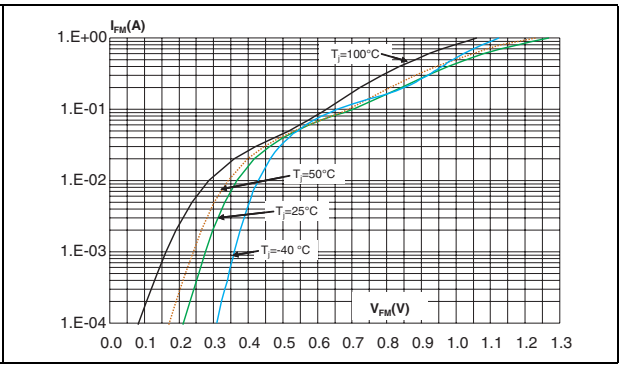


Figure 7. Thermal resistance junction to ambient versus copper surface under each lead - epoxy FR4 with recommended pad layout, e_{CU} = 35 µm (SOD-323)

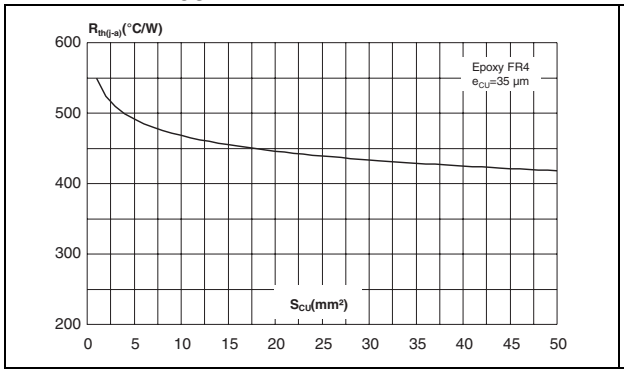


Figure 8. Relative variation of thermal impedance junction to ambient versus pulse duration - epoxy FR4 with recommended pad layout, e_{CU} = 35 µm (SOD-323)

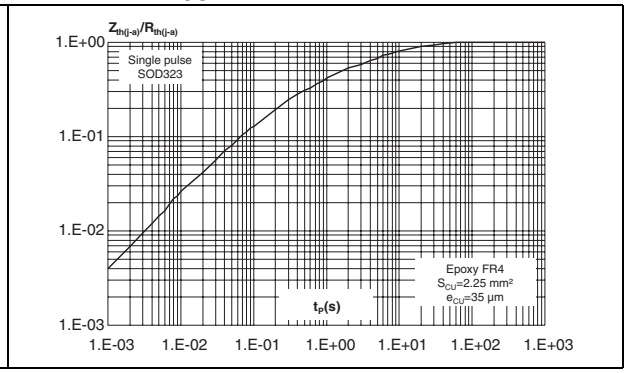


Figure 9. Relative variation of thermal impedance junction to ambient versus pulse duration - aluminium oxide substrate 10 mm x 8 mm x 0.5 mm (SOT-23)

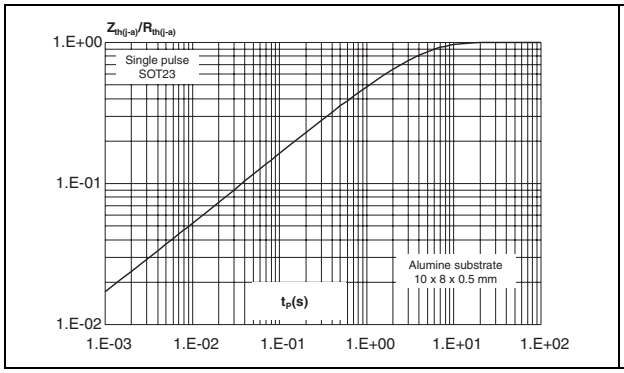


Figure 10. Relative variation of thermal impedance junction to ambient versus pulse duration - epoxy FR4 with recommended pad layout, e_{CU} = 35 µm (SOD-523)

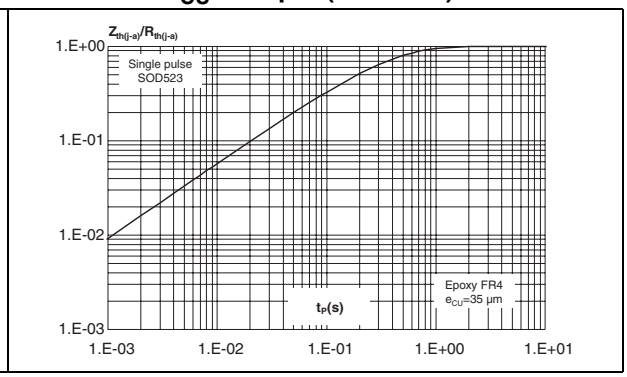
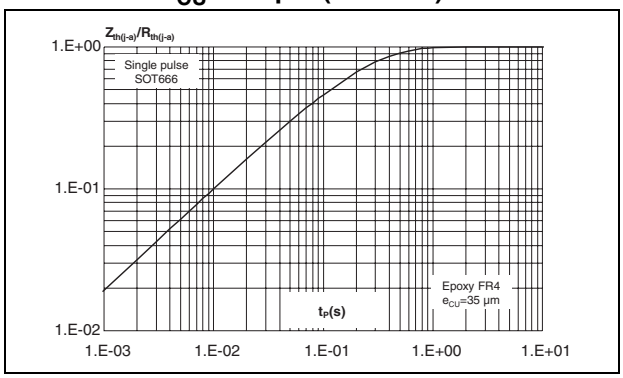
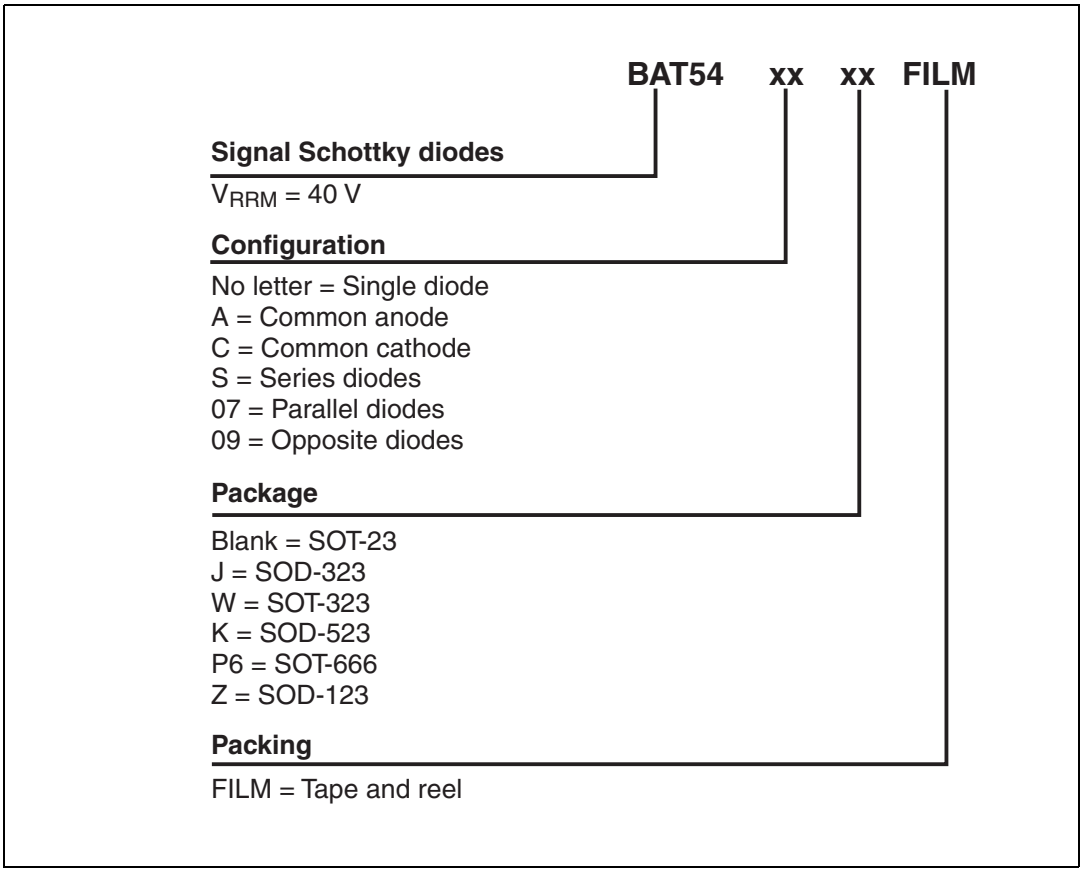


Figure 11. Relative variation of thermal impedance junction to ambient versus pulse duration - epoxy FR4 with recommended pad layout, e_{CU} = 35 µm (SOT-666)



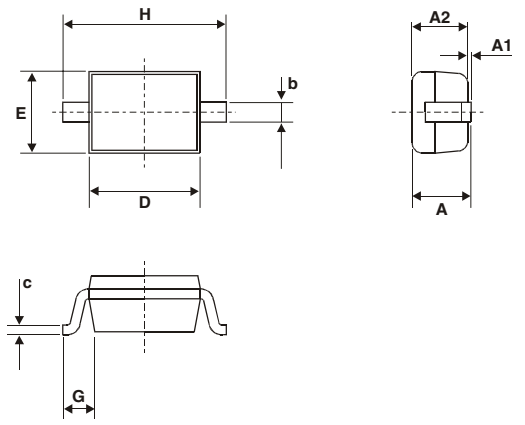
2 Ordering information scheme



3 Package information

Epoxy meets UL94, V0

Table 5. SOD-123 dimensions



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A		1.45		0.057
A1	0	0.1	0	0.004
A2	0.85	1.35	0.033	0.053
b	0.55 Typ.		0.022 Typ.	
c	0.15 Typ.		0.039 Typ.	
D	2.55	2.85	0.1	0.112
E	1.4	1.7	0.055	0.067
G	0.25		0.01	
H	3.55	3.95	0.14	0.156

Figure 12. SOD-123 footprint (dimensions in mm)

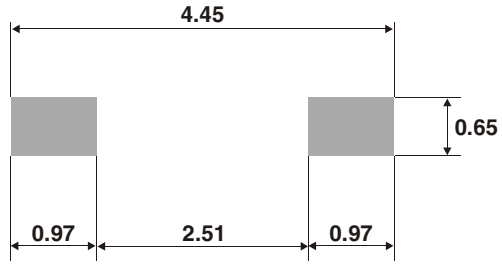
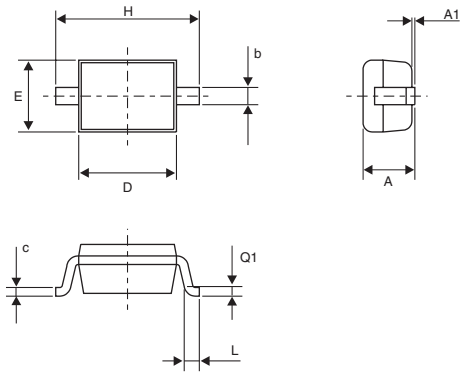


Table 6. SOD-323 dimensions



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A		1.17		0.046
A1	0	0.1	0	0.004
b	0.25	0.44	0.01	0.017
c	0.1	0.25	0.004	0.01
D	1.52	1.8	0.06	0.071
E	1.11	1.45	0.044	0.057
H	2.3	2.7	0.09	0.106
L	0.1	0.46	0.004	0.02
Q1	0.1	0.41	0.004	0.016

Figure 13. SOD-323 footprint (dimensions in mm)

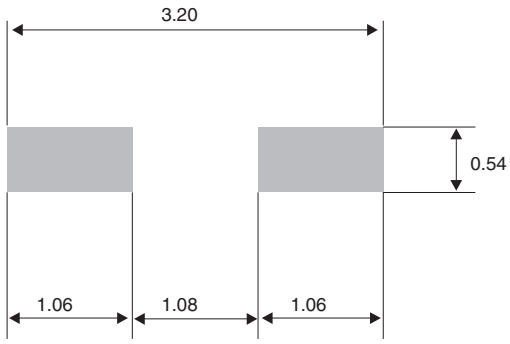
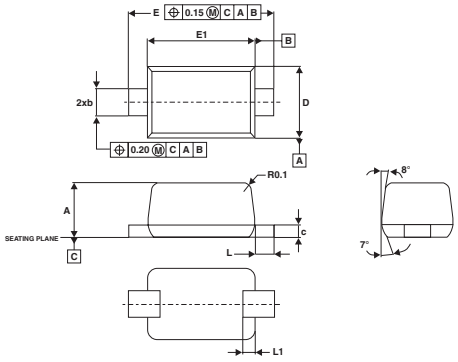


Table 7. SOD-523 dimensions



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.50	0.60	0.70	0.020	0.024	0.028
E	1.50	1.60	1.70	0.059	0.063	0.067
E1	1.10	1.20	1.30	0.043	0.047	0.051
D	0.70	0.80	0.90	0.028	0.031	0.035
b	0.25		0.35	0.010		0.014
c	0.07		0.20	0.003		0.008
L	0.15	0.20	0.25	0.006	0.008	0.010
L1	0.10		0.20	0.004		0.008

Figure 14. SOD-523 footprint (dimensions in mm)

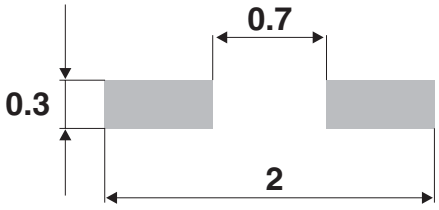
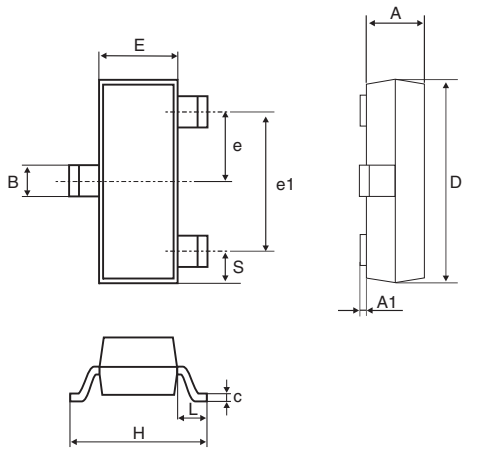


Table 8. SOT-23 dimensions



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.89	1.4	0.035	0.055
A1	0	0.1	0	0.004
B	0.3	0.51	0.012	0.02
c	0.085	0.18	0.003	0.007
D	2.75	3.04	0.108	0.12
e	0.85	1.05	0.033	0.041
e1	1.7	2.1	0.067	0.083
E	1.2	1.6	0.047	0.063
H	2.1	2.75	0.083	0.108
L	0.6 typ.		0.024 typ.	
S	0.35	0.65	0.014	0.026

Figure 15. SOT-23 footprint (dimensions in mm)

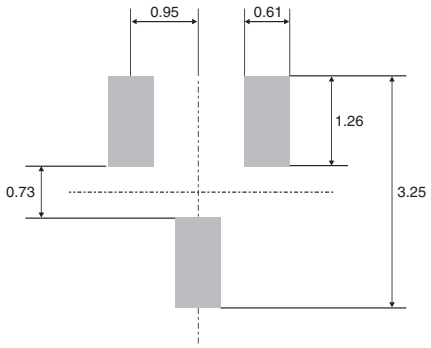
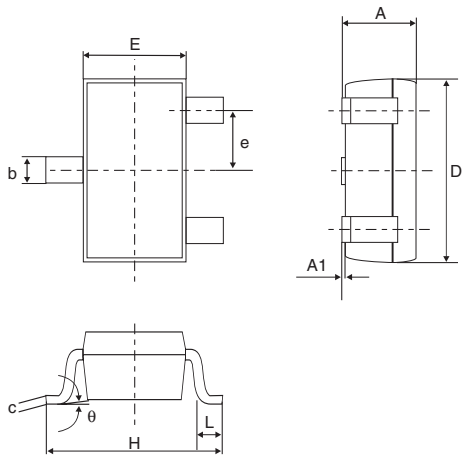


Table 9. SOT-323 dimensions



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.8		1.1	0.031		0.043
A1	0.0		0.1	0.0		0.004
b	0.25		0.4	0.010		0.016
c	0.1		0.26	0.004		0.010
D	1.8	2.0	2.2	0.071	0.079	0.086
E	1.15	1.25	1.35	0.045	0.049	0.053
e		0.65			0.026	
H	1.8	2.1	2.4	0.071	0.083	0.094
L	0.1	0.2	0.3	0.004	0.008	0.012
q	0		30°	0		30°

Figure 16. SOT-323 footprint (dimensions in mm)

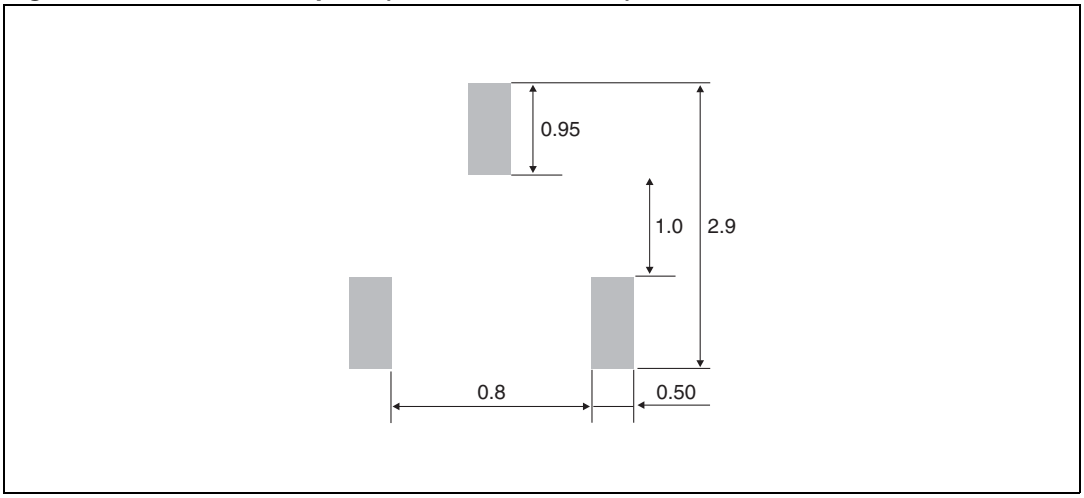
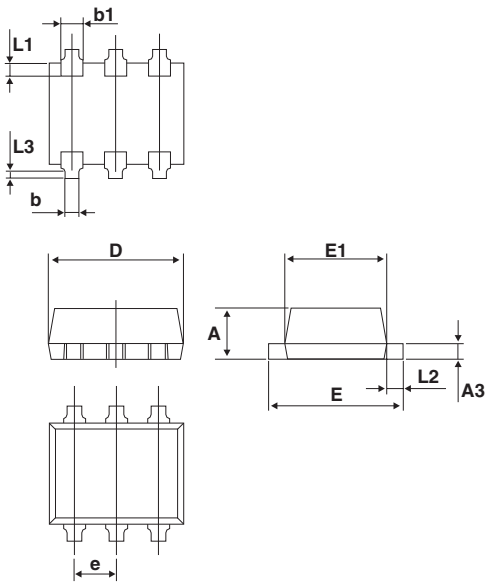
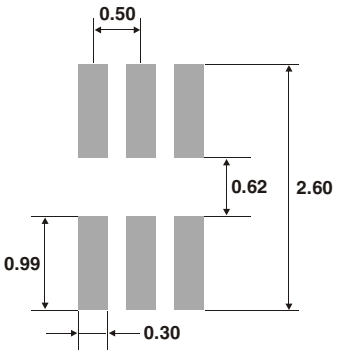


Table 10. SOT-666 dimensions



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.45		0.60	0.018		0.024
A3	0.08		0.18	0.003		0.007
b	0.17		0.34	0.007		0.013
b1	0.19	0.27	0.34	0.007	0.011	0.013
D	1.50		1.70	0.059		0.067
E	1.50		1.70	0.059		0.067
E1	1.10		1.30	0.043		0.051
e		0.50			0.020	
L1		0.19			0.007	
L2	0.10		0.30	0.004		0.012
L3		0.10			0.004	

Figure 17. SOT-666 footprint (dimensions in mm)



In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

4 Ordering information

Part Number	Marking	Package	Weight	Base qty	Delivery mode
BAT54FILM	D86	SOT-23 Single	10 mg	3000	Tape and reel
BAT54SFILM	D88	SOT-23 Serial	10 mg	3000	Tape and reel
BAT54CFILM	D87	SOT-23 Common cathode	10 mg	3000	Tape and reel
BAT54AFILM	D84	SOT-23 Common anode	10 mg	3000	Tape and reel
BAT54WFILM	D73	SOT-323 Single	6 mg	3000	Tape and reel
BAT54SWFILM	D78	SOT-323 Serial	6 mg	3000	Tape and reel
BAT54CWFILM	D77	SOT-323 Common cathode	6 mg	3000	Tape and reel
BAT54AWFILM	D74	SOT-323 Common anode	6 mg	3000	Tape and reel
BAT54JFILM	86	SOD-323	5 mg	3000	Tape and reel
BAT54KFILM	86	SOD-523	1.4 mg	3000	Tape and reel
BAT54-07P6FILM	P4	SOT-666 Parallel	2.9 mg	3000	Tape and reel
BAT54-09P6FILM	Q4	SOT-666 Opposite	2.9 mg	3000	Tape and reel
BAT54ZFILM	D72	SOD-123	10 mg	3000	Tape and reel

5 Revision history

Date	Revision	Description of Changes
Jun-1999	8	Last update.
24-Jul-2006	9	BAT54, A, C, S and BAT54J / W / AW / CW /SW datasheets merged. ECOPACK statement added. SOD-123, SOD-523 and SOT-666 packages added.

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